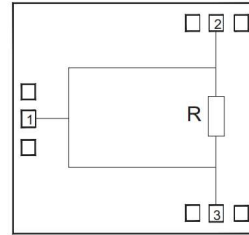


Performance

- Frequency: 12~18GHz
- Insertion loss: 0.5dB
- Chip size: 2.30*1.20*0.1mm

Function Diagram

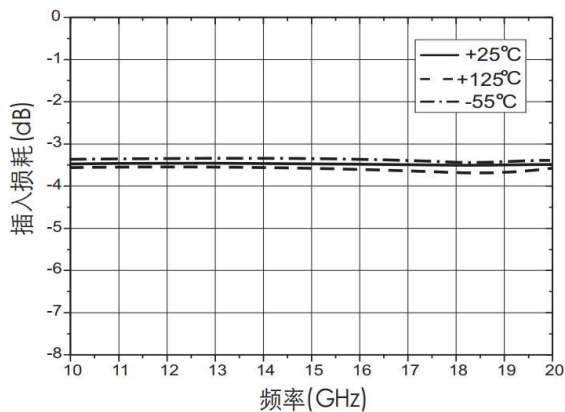


Electrical Specifications (Ta=+25°C, 50Ω system)

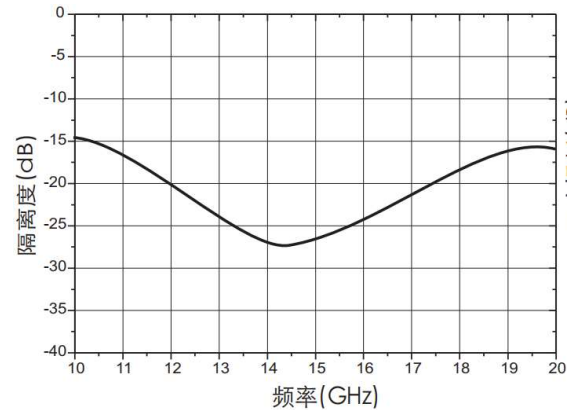
Parameter	Min	Typical	Max	Unit
Frequency Range	12~18			GHz
Insertion Loss	0.4	0.5	0.6	dB
Insertion Loss Ripple	-	±0.1	-	dB
Isolation	18	22	-	dB
Input Return Loss	16	18	-	dB
Output Return Loss	20	20	-	dB

Test Curves

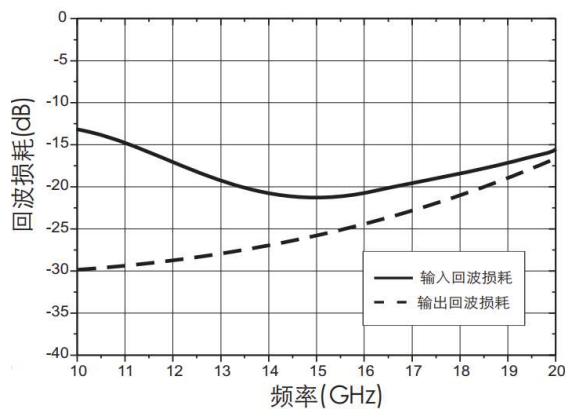
Insertion loss vs. Freq



Isolation vs. Freq



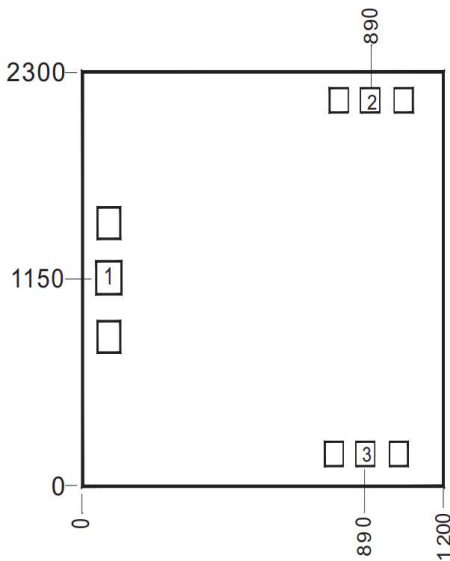
Input/Output Return Loss vs. Freq



Absolute Max Ratings

Parameter	Value
Input Signal Power	+37dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C
Static protection Grade (HBM)	Class 1A

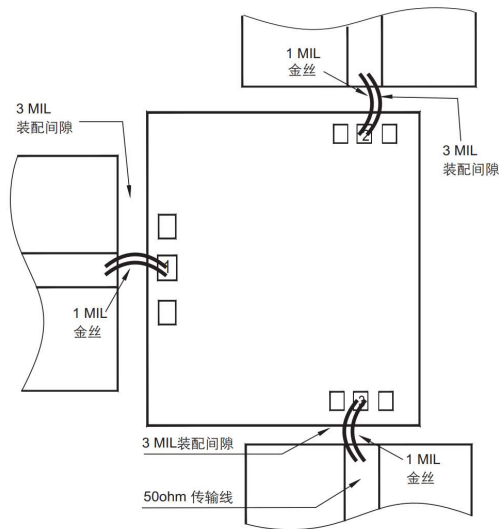
Outline Size



Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated
Pads size: 100*100 um
5. Don't bonding on thru holds
6. Tolerance: ±50um

Assembly Diagram



Bonding Definition

No.	Number	Description
1	IN	RF input, 50ohm
2,3	Out1,Out2	RF output, 50ohm
	GND	Bottom must be grounded